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**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20658**Generic Copy

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**Issue Date:** 01-Oct-2014

**TITLE:** Assembly location change from Sigurd (formerly Meicer) to ASE for NOA1212 and the 1.6x1.6mm 6-lead CUDFN package.

**PROPOSED FIRST SHIP DATE:** 08-Jan-2015 or earlier with customer acceptance

**AFFECTED CHANGE CATEGORY(S):** Assembly location

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact Product Engineer Antonio Oblea <[Antonio.Oblea@onsemi.com](mailto:Antonio.Oblea@onsemi.com)> or Business Operations Manager Rusty Winzenread <[Rusty.Winzenread@onsemi.com](mailto:Rusty.Winzenread@onsemi.com)>.

**SAMPLES:** Contact your local ON Semiconductor Sales Office

**ADDITIONAL RELIABILITY DATA:**

Contact Product Engineer Antonio Oblea <[Antonio.Oblea@onsemi.com](mailto:Antonio.Oblea@onsemi.com)> or Business Operations Manager Rusty Winzenread <[Rusty.Winzenread@onsemi.com](mailto:Rusty.Winzenread@onsemi.com)>

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.

**DESCRIPTION AND PURPOSE:**

ON Semiconductor's assembly operations for NOA1212 and the 1.6x1.6mm 6-lead CUDFN package is transferring to ASE.



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### RELIABILITY DATA SUMMARY:

Test	Name	Test Conditions	End Point Req's	Test Results	(rej/ ss)
				Read Point	Lot A
PC	MSL3 Preconditioning	3 IR @ 260 deg C	c = 0, Room		0/146*
TC	Temp Cycle	-40/+85 C	c = 0, Room	1000 cyc	0/66*
THU	Unbiased Temp Humidity	Temp= +85°C RH=85% unbiased	c = 0, Room	500 hrs	0/69*
RSH	Resistance to Solder Heat	260 C Immersion	c = 0, Room	Electrical	
SAT	Scanning Acoustic Tomography	Compare for Delamination before and after PC	Compare to existing data	Results	0/5
BPS	Bond Pull Strength	Cond C.	Min Cpk 1.33	Results	pass
BS	Bond Shear		Min Cpk 1.33	Results	pass

\*Failures were observed for illumination sensitivity. Parts that failed had contamination on the top surface. Evaluation was performed and documented in FA report 442368. Failures were caused by handling and not by package or die and so were discounted in the qualification results.

### CHANGED PART IDENTIFICATION:

Parts processed at new assembly location will have a package date code newer than or equal to 1438. Units processed at old assembly location do not have package marking.

### List of affected General Parts:

NOA1212CUTAG